

General Description

_Features

The MAX2850 is a single-chip, 4-channel RF transmitter IC designed for 5GHz wireless HDMI applications. The IC includes all circuitry required to implement the complete 4-channel MIMO RF transmitter function and crystal oscillator, providing a fully integrated transmit path, VCO, frequency synthesis, and baseband/control interface. It includes a fast-settling, sigma-delta RF fractional synthesizer with 76Hz frequency programming step size. The IC also integrates on-chip I/Q amplitude and phase-error calibration circuits. Dynamic on/off control of four external PAs is implemented with programmable precision voltages. A 4-to-1 analog mux routes external PA power-detect voltages to the RSSI pin.

On-chip monolithic filters are included for transmitter I/Q baseband signal reconstruction to support both 20MHz and 40MHz RF channels. The baseband filtering and Tx signal paths are optimized to meet stringent WHDI requirements. The upconverter local oscillator is coherent among all the transmitter channels.

The reverse-link control channel uses an on-chip 5GHz OFDM receiver. It shares the RF synthesizer and LO generation circuit with the MIMO transmitters. The receiver includes both an in-channel RSSI and an RF RSSI.

The MIMO transmitter chip is housed in a small, 68-pin thin QFN leadless plastic package with exposed pad.

_Applications

5GHz Wireless HDMI (WHDI) 5GHz FDD Backhaul and WiMax[™] 5GHz MIMO Transmitter Up to Four Spatial Streams

5GHz Beam Steering Transmitter

- 5GHz 4x MIMO Downlink Transmitters, Single Uplink IEEE 802.11a Receiver 4900MHz to 5900MHz Frequency Range -5dBm Transmit Power (54Mbps OFDM) **Coherent LO Among Transmitters** 31dB Tx Gain-Control Range with 0.5dB Step Size, Digitally Controlled Tx/Rx I/Q Error and LO Leakage Detection and Adjustment Programmable 20MHz/40MHz Tx I/Q Lowpass Anti-Aliasing Filter 4-to-1 Analog Mux for PA Power Detect 4-Channel PA On/Off Control 4.5dB Rx Noise Figure 70dB Rx Gain-Control Range with 2dB Step Size, Digitally Controlled 60dB Dynamic Range Receiver RSSI **RF Wideband Receiver RSSI** Programmable 20MHz/40MHz Rx I/Q Lowpass **Channel Filters** Sigma-Delta Fractional-N PLL with 76Hz Resolution Monolithic Low-Noise VCO with -35dBc **Integrated Phase Noise** 4-Wire SPI[™] Digital Interface I/Q Analog Baseband Interface **Digital Tx/Rx Mode Control On-Chip Digital Temperature Sensor Readout Complete Baseband Interface Digital Tx/Rx Mode Control**
- ♦ +2.7V to +3.6V Supply Voltage
- Small, 68-Pin Thin QFN Package (10mm x 10mm)

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX2850ITK+	-25°C to +85°C	68 Thin QFN-EP*

*EP = Exposed pad.

+Denotes a lead(Pb)-free/RoHS-compliant package.

MAX2850

WiMax is a trademark of WiMax Forum. SPI is a trademark of Motorola, Inc.

Typical Operating Circuit appears at end of data sheet.

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

VCC_ Pins to GND-0.3V to +3.9V RF Inputs Maximum Current: RXRF+, RXRFto GND-1mA to +1mA RF Outputs: TXRF1+, TXRF1-, TXRF2+, TXRF2-, TXRF3+, TXRF3-, TXRF4+, TXRF4- to GND....-0.3V to +3.9V Analog Inputs: TXBB1I+, TXBB1I-, TXBB1Q+, TXBB1Q-, TXBB2I+, TXBB2I-, TXBB2Q+, TXBB2Q-, TXBB3I+, TXBB3I-, TXBB3Q+, TXBB3Q-, TXBB4I+, TXBB4I-, TXBB4Q+, TXBB4Q-, PA_DET1, PA_DET2, PA_DET3, PA_DET4, XTAL, XTAL_CAP to GND-0.3V to +3.9V Analog Outputs: RXBBI+, RXBBI-, RXBBQ+, RXBBQ-, RSSI, CLKOUT2, VCOBYP, CPOUT+, CPOUT-, PA_BIAS1, PA_BIAS2, PA_BIAS3, PA_BIAS4 to GND-0.3V to +3.9V Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION! ESD SENSITIVE DEVICE

DC ELECTRICAL CHARACTERISTICS

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, ENABLE set according to operating mode, \overline{CS} = high, SCLK = DIN = low, transmitter in maximum gain, $T_A = -25^{\circ}C$ to $+85^{\circ}C$. Power matching and termination for the differential RF output pins using the *Typical Operating Circuit*. 100mV_{RMS} differential I and Q signals applied to I/Q baseband inputs of transmitters in transmit mode. Typical values measured at V_{CC} = 2.85V, $T_A = +25^{\circ}C$, LO frequency = 5.35GHz, $T_A = +25^{\circ}C$. Channel bandwidth is set to 40MHz. PA control pins open circuit, V_{CC} PA BIAS is disconnected.) (Note 1)

PARAMETERS	CONE	DITIONS	MIN	ТҮР	MAX	UNITS
Supply Voltage, V _{CC}			2.7		3.6	V
	Shutdown mode	$T_A = +25^{\circ}C$		10		μA
	Clock-out only mode	XTAL oscillator, load = 10pF		3		
		TCXO input, load = 10kΩll10pF		7.4	11	
Supply Current	Standby mode			60	89]
Supply Current	Transmit mode	One transmitter is on		188	235	mA
		Four transmitters are on		505	661]
	Receive mode			135	174]
	Transmit calibration mode	One transmitter is on		214	261]
		Four transmitters are on		532	686]
	Receive calibration mode	·		268	327	1
Rx I/Q Output Common-Mode Voltage			0.9	1.1	1.3	V
Tx Baseband Input Common- Mode Voltage Operating Range			0.5		1.1	V
Tx Baseband Input Bias Current	Source current			10	20	μA

DC ELECTRICAL CHARACTERISTICS (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, ENABLE set according to operating mode, \overline{CS} = high, SCLK = DIN = low, transmitter in maximum gain, TA = -25°C to +85°C. Power matching and termination for the differential RF output pins using the *Typical Operating Circuit*. 100mV_{RMS} differential I and Q signals applied to I/Q baseband inputs of transmitters in transmit mode. Typical values measured at V_{CC} = 2.85V, T_A = +25°C, LO frequency = 5.35GHz, T_A = +25°C. Channel bandwidth is set to 40MHz. PA control pins open circuit, V_{CC}-PA_BIAS is disconnected.) (Note 1)

PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNITS
LOGIC INPUTS: ENABLE, SCLK,	DIN, CS				
Digital Input-Voltage High, VIH		V _{CC} - 0.4			V
Digital Input-Voltage Low, VIL				0.3	V
Digital Input-Current High, IIH		-1		+1	μA
Digital Input-Current Low, IIL		-1		+1	μA
LOGIC OUTPUTS: DOUT, CLKOU	TL				
Digital Output-Voltage High, VOH	Sourcing 1mA	V _{CC} - 0.4			V
Digital Output-Voltage Low, VOL	Sinking 1mA			0.4	V
Digital Output Voltage in Shutdown Mode	Sinking 1mA		Vol		V

AC ELECTRICAL CHARACTERISTICS—Rx MODE

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, RF frequency = 5.351GHz, T_A = -25°C to +85°C. LO frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, with power matching at RXRF+ and RXRF- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at 100mV_{RMS} loaded with 10k Ω differential load resistance and 10pF load capacitance. The RSSI pin is loaded with 10k Ω load resistance to ground. Typical values measured at V_{CC} = 2.85V, channel bandwidths of 40MHz, T_A = +25°C.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS				
RECEIVER SECTION: RF INPUT TO I/Q BASEBAND LOADED OUTPUT (Includes 50Ω to 100Ω RF Balun and Matching)									
RF Input Frequency Range		4.9		5.9	GHz				
Peak-to-Peak Gain Variation over RF Frequency Range at	4.9GHz to 5.35GHz		0.3	2.6	— dB				
One Temperature	5.35GHz to 5.9GHz		2.2	5.3	UD UD				
RF Input Return Loss	All LNA settings		-6		dB				
Total Voltage Gain	Maximum gain; Main address 1 D7:0 = 11111111	61	68		dB				
	Minimum gain; Main address 1 D7:0 = 00000000		-2	+5	uв				
	Main address 1 D7:D5 = 110		-8						
RF Gain Steps Relative to	Main address 1 D7:D5 = 101		-16		dB				
Maximum Gain	Main address 1 D7:D5 = 001		-32		uБ				
	Main address 1 D7:D5 = 000		-40						
Baseband Gain Range	From maximum baseband gain (Main address 1 D3:D0 = 1111) to minimum baseband gain (Main address 1 D3:D0 = 0000)	27.5	30	32.5	dB				
Baseband Gain Step			2		dB				
RF Gain Change Settling Time	Gain settling to within ± 0.5 dB of steady state; RXHP = 1		400		ns				

AC ELECTRICAL CHARACTERISTICS—Rx MODE (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, RF frequency = 5.351GHz, T_A = -25°C to +85°C. LO frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, with power matching at RXRF+ and RXRF- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at 100mV_{RMS} loaded with 10k Ω differential load resistance and 10pF load capacitance. The RSSI pin is loaded with 10k Ω load resistance to ground. Typical values measured at V_{CC} = 2.85V, channel bandwidths of 40MHz, T_A = +25°C.) (Note 1)

PARAMETER	CC	CONDITIONS		TYP	MAX	UNITS
Baseband Gain-Change Settling Time	Gain settling to within ±	0.5dB of steady state; RXHP = 1		200		ns
	Balun input referred, integrated from 10kHz to 9.5MHz at I/Q base-	Maximum RF gain (Main address 1 D7:D5 = 111)		4.5		
DSB Noise Figure	band output for 20MHz RF bandwidth	Maximum RF gain - 16dB (Main address 1 D7:D5 = 101)		15		dB
Dob Noise Figure	Balun input referred, integrated from 10kHz to 19MHz at I/Q base-	Maximum RF gain (Main address 1 D7:D5 = 111)		4.5		
	band output for 40MHz RF bandwidth	Maximum RF gain - 16dB (Main address 1 D7:D5 = 101)		15		
	20MHz RF channel;	-65dBm wanted signal; RF gain = max (Main address 1 D7:D0 = 11101001)		-13		
	two tone jammers at +25MHz and +48MHz frequency offset with -39dBm/tone 40MHz RF channel; two tone jammers at +50MHz and +96MHz	-49dBm wanted signal; RF gain = max - 16dB (Main address 1 D7:D0 = 10101001)		-5		
		-45dBm wanted signal; RF gain = max - 32dB (Main address 1 D7:D0 = 00111111)		11		
Out-of-Band Input IP3		-65dBm wanted signal; RF gain = max (Main address 1 D7:D0 = 11101001)		-13		- dBm
		-49dBm wanted signal; RF gain = max - 16dB (Main address 1 D7:D0 = 10101001)		-5		
	-39dBm/tone	-45dBm wanted signal; RF gain = max - 32dB (Main address 1 D7:D0 = 00101001)		11		
1dB Gain Desensitization by	Blocker at ±40MHz offse channel	et frequency for 20MHz RF		-24		dDree
Alternate Channel Blocker	Blocker at ±80MHz offse channel	et frequency for 40MHz RF		-24		- dBm
	Max RF gain (Main addı	ress 1 D7:D5 = 111)		-32		
Input 1dB Gain Compression	Max RF gain - 8dB (Mai	n address 1 D7:D5 = 110)		-24		dBm
	Max RF gain - 16dB (Ma	ain address 1 D7:D5 = 101)		-16		
	Max RF gain - 32dB (Ma	ain address 1 D7:D5 = 001)		0		
Output 1dB Gain Compression	Over passband frequen 1dB compression point	cy range; at any gain setting;		0.63		VP-P

AC ELECTRICAL CHARACTERISTICS—Rx MODE (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, RF frequency = 5.351GHz, T_A = -25° C to $+85^{\circ}$ C. LO frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, with power matching at RXRF+ and RXRF- differential ports using the *Typical Operating Circuit*. Receiver I/Q output at 100mV_{RMS} loaded with 10k Ω differential load resistance and 10pF load capacitance. The RSSI pin is loaded with 10k Ω load resistance to ground. Typical values measured at V_{CC} = 2.85V, channel bandwidths of 40MHz, T_A = $+25^{\circ}$ C.) (Note 1)

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Baseband -3dB Lowpass Corner	Main address 0 D1 = 0		9.5		MHz
Frequency	Main address 0 D1 = 1		19		
Baseband Filter Stopband	Rejection at 30MHz offset frequency for 20MHz channel	57	70		- dB
Rejection	Rejection at 60MHz offset frequency for 40MHz channel	57	70		UD
Baseband -3dB Highpass Corner	Main address 5 D1 = 1		600		- kHz
Frequency	Main address 5 D1 = 0		10		КПИ
Steady-State I/Q Output DC Error with AC-Coupling	$50\mu s$ after enabling receive mode and toggling RxHP from 1 to 0, averaged over many measurements if I/Q noise voltage exceeds $1mV_{RMS}$, at any given gain setting, no input signal, 1-sigma value		2		mV
I/Q Gain Imbalance	1MHz baseband output, 1-sigma value		0.1		dB
I/Q Phase Imbalance	1MHz baseband output, 1-sigma value		0.2		degrees
Sideband Suppression	1MHz baseband output (Note 2)		40		dB
	LO frequency		-75		
Receiver Spurious Signal	2 x LO frequency		-62		dBm/
Emissions	3 x LO frequency		-75		MHz
	4 x LO frequency		-60		
RF RSSI Output Voltage	-20dBm input power		1.75		V
Baseband RSSI Slope		19.5	26.5	35.5	mV/dB
Baseband RSSI Maximum Output Voltage			2.3		V
Baseband RSSI Minimum Output Voltage			0.5		V
RF Loopback Conversion Gain	Tx VGA gain at maximum (Main address 9 D9:D4 = 111111); Rx VGA gain at maximum - 24dB (Main address 1 D3:D0 = 0101)	-6	+2	+10	dB

AC ELECTRICAL CHARACTERISTICS—Tx MODE

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, RF frequency = 5.351GHz, T_A = -25°C to +85°C. LO frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, with power matching at TXRF+ and TXRF- differential ports using the *Typical Operating Circuit*. 100mV_{RMS} sine and cosine signal applied to I/Q baseband inputs of transmitter (differential DC-coupled). Typical values measured at V_{CC} = 2.85V, channel bandwidths of 40MHz, T_A = +25°C.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS				
TRANSMIT SECTION: Tx BASEBAND I/Q INPUTS TO RF OUTPUTS (Includes Matching and Balun Loss)									
RF Output Frequency Range		4.9		5.9	GHz				
Peak-to-Peak Gain Variation over RF Band	At one temperature		3	6.4	dB				

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AC ELECTRICAL CHARACTERISTICS—Tx MODE (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, RF frequency = 5.351GHz, T_A = -25°C to +85°C. LO frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, with power matching at TXRF+ and TXRF- differential ports using the *Typical Operating Circuit*. 100mV_{RMS} sine and cosine signal applied to I/Q baseband inputs of transmitter (differential DC-coupled). Typical values measured at V_{CC} = 2.85V, channel bandwidths of 40MHz, T_A = +25°C.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Maximum Output Power	20MHz OFDM signal conforming to spectral emission mask and -34dB EVM	-4			- dBm
Maximum Output Fower	40MHz OFDM signal conforming to spectral emission mask and -34dB EVM		-4		
Output 1dB Gain Compression	Relative to typical maximum output power at 9.5MHz input frequency		11		dBc
Input 1dB Gain Compression	At 19MHz input frequency, over input common-mode voltage between 0.5V and 1.1V	380		mVRMS	
Gain-Control Range		26	31.5	34.5	dB
Gain-Control Step			0.5		dB
RF Output Return Loss			-3		dB
Unwanted Sideband	Over RF channel, RF frequency, baseband frequency, and gain settings (Note 2)		-40		dBc
Carrier Leakage	Over RF channel, RF frequency, and gain settings (Note 2)		-29	-15	dBc
	Minimum differential resistance		60		kΩ
Tx I/Q Input Impedance (RIIC)	Maximum differential capacitance		2		pF
Baseband Filter Stopband	At 30MHz frequency offset for 20MHz RF channel		86		
Rejection	At 60MHz frequency offset for 40MHz RF channel		67		- dB
Tx Calibration Ftone Level	At Tx gain code (Main address 9 D9:D4) = 100010 and -15dBc carrier leakage (Local address 27 D2:D0 = 110 and Main address 1 D3:D0 = 0000)	-28		dBV _{RMS}	
Tx Calibration Gain Range	Adjust Local address 27 D2:D0		35		dB

AC ELECTRICAL CHARACTERISTICS—FREQUENCY SYNTHESIS

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, frequency = 5.35GHz, $T_A = -25^{\circ}C$ to +85°C. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low. Typical values measured at V_{CC} = 2.85V, LO frequency = 5.35GHz, T_A = +25°C.) (Note 1)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
FREQUENCY SYNTHESIZER					
RF Channel Center Frequency		4.9		5.9	GHz
Channel Center Frequency Programming Step			76.294		Hz
Closed-Loop Integrated Phase Noise	Loop BW = 200kHz, integrate phase noise from 1kHz to 10MHz		-35		dBc
Charge-Pump Output Current			0.8		mA
Spur Loval	fOFFSET = 0 to 19MHz		-42		- dBc
Spur Level	foffset = 40MHz		-66		
Reference Frequency			40		MHz

AC ELECTRICAL CHARACTERISTICS—FREQUENCY SYNTHESIS (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, $T_A = -25^{\circ}C$ to $+85^{\circ}C$, frequency = 5.35GHz. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low; typical values measured at V_{CC} = 2.85V, T_A = +25°C, LO frequency = 5.35GHz.) (Note 1)

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Reference Frequency Input Levels	AC-coupled to XTAL pin	800			mVp-p
Maximum Crystal Motional Resistance			50		Ω
Crystal Capacitance Tuning Range	Base-to-ground capacitance		30		pF
Crystal Capacitance Tuning Step			140		fF
CLKOUT Signal Level	10pF load capacitance	VCC - 0.8	VCC - 0.1		Vp-p

AC ELECTRICAL CHARACTERISTICS—MISCELLANEOUS BLOCKS

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, $T_A = -25^{\circ}C$ to $+85^{\circ}C$. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low. Typical values measured at $V_{CC} = 2.85V$, $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
PA POWER DETECTOR MUX						
Output-Voltage Drop	$V_{IN} = 2V$, load resistance = $10k\Omega$	2 to ground		11	30	mV
PA ON/OFF CONTROL	·					
V _{CC_PA} Input Voltage Range			3.1		3.6	V
VCC_PA Supply Current	With 10mA load at PA_BIAS1 to	PA_BIAS4 42				mA
Output High Level	10mA load current, Main address	10mA load current, Main address 11 D7:5 = 011				V
Output High-Level Variation Between PA_BIAS1 to PA_BIAS4				30		mV
Output Low Level	1mA load current, Main address	11 D7:5 = 011		25		mV
Turn-On Time	Measured from CS rising edge			0.3		μs
ON-CHIP TEMPERATURE SENS	OR					
		$T_A = +25^{\circ}C$		17		
Digital Output Code	Read-out at DOUT pin through Main address 3 D4:D0	$T_A = +85^{\circ}C$		25]
		TA = -20°C		9]

AC ELECTRICAL CHARACTERISTICS—TIMING

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, frequency = 5.35GHz, $T_A = -25^{\circ}C$ to +85°C. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low. Typical values measured at V_{CC} = 2.85V, LO frequency = 5.35GHz, T_A = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SYSTEM TIMING						
Shutdown Time				2		μs
Maximum Channel Switching Time		Loop bandwidth = 200kHz, settling to within ±1kHz from steady state		2		ms
Maximum Channel Switching Time With Preselected VCO Sub-Band		Loop bandwidth = 200kHz, settling to within ±1kHz from steady state		56		μs

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AC ELECTRICAL CHARACTERISTICS—TIMING (continued)

(Operating conditions, unless otherwise specified: $V_{CC} = 2.7V \sim 3.6V$, frequency = 5.35GHz, $T_A = -25^{\circ}C$ to +85°C,. Reference frequency = 40MHz, ENABLE = high, \overline{CS} = high, SCLK = DIN = low, typical values measured at $V_{CC} = 2.85V$, LO frequency = 5.35GHz, $T_A = +25^{\circ}C$.) (Note 1)

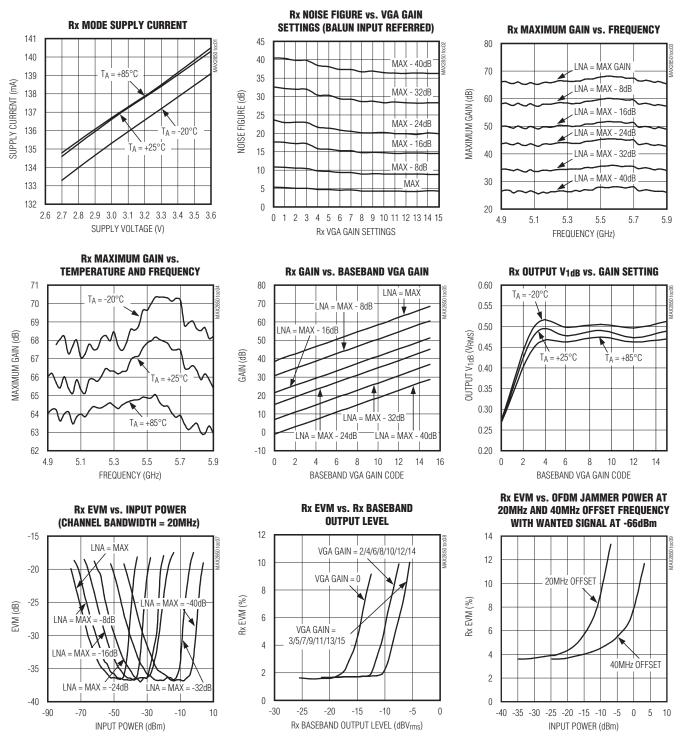
PARAMETER	SYMBOL	SYMBOL CONDITIONS			ТҮР	MAX	UNITS
		Measured	Rx to Tx mode, Tx gain settles to within 0.2dB of steady state		2		
Rx/Tx Turnaround Time		from CS ris- ing edge	Tx to Rx mode with RXHP = 1, Rx gain settles to within 0.5dB of steady state		2		μs
Tx Turn-On Time (from Standby Mode)			om $\overline{\text{CS}}$ rising edge, Tx gain settles IB of steady state		2		μs
Tx Turn-Off Time (to Standby Mode)		From $\overline{\text{CS}}$ risir	ng edge		0.1		μs
Rx Turn-On Time (from Standby Mode)			om CS rising edge, Rx gain settles IB of steady state		2		μs
Rx Turn-Off Time (to Standby Mode)		From \overline{CS} risir	ng edge		0.1		μs
4-WIRE SERIAL-INTERFACE	TIMING (See	Figure 1)					
SCLK Rising Edge to \overline{CS} Falling Edge Wait Time	tcso				6		ns
Falling Edge of CS to Rising Edge of First SCLK Time	tCSS				6		ns
DIN to SCLK Setup Time	tDS				6		ns
DIN to SCLK Hold Time	tDН				6		ns
SCLK Pulse-Width High	tСН				6		ns
SCLK Pulse-Width Low	tCL				6		ns
Last Rising Edge of SCLK to Rising Edge of \overline{CS} or Clock to Load Enable Setup Time	tСSH				6		ns
CS High Pulse Width	tcsw				50		ns
Time Between Rising Edge of CS and the Next Rising Edge of SCLK	tCS1				6		ns
SCLK Frequency	fCLK					40	MHz
Rise Time	t _R				2.5		ns
Fall Time	t⊢				2.5		ns
SCLK Falling Edge to Valid DOUT	tD				12.5		ns

Note 1: The MAX2850 is production tested at $T_A = +25^{\circ}$ C; minimum/maximum limits at $T_A = +25^{\circ}$ C are guaranteed by test, unless specified otherwise. Minimum/maximum limits at $T_A = -25^{\circ}$ C and $+85^{\circ}$ C are guaranteed by design and characterization. There is no power-on register settings self-reset; recommended register settings must be loaded after V_{CC} is applied.

Note 2: For optimal Rx and Tx quadrature accuracy over temperature, the user can utilize the Rx calibration and Tx calibration circuit to assist quadrature calibration.

Typical Operating Characteristics

 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$



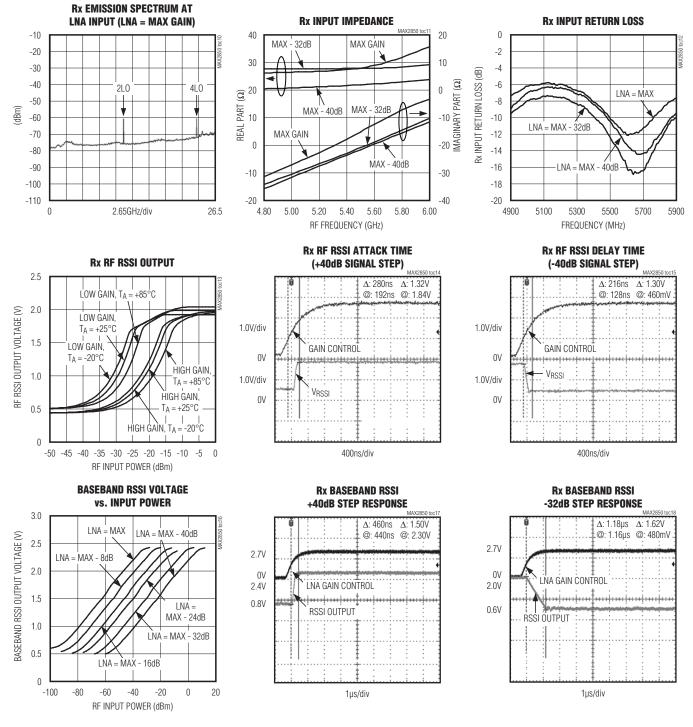
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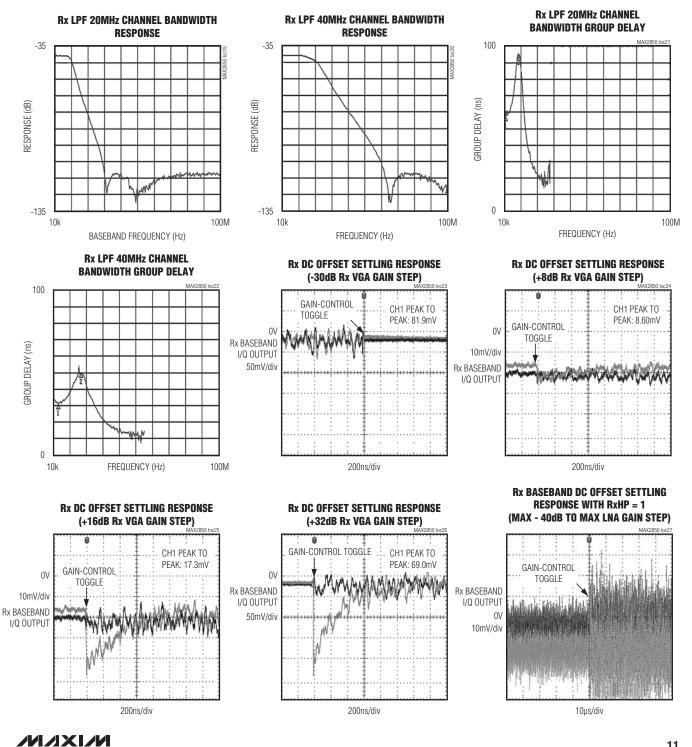
Typical Operating Characteristics (continued)

 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$



Typical Operating Characteristics (continued)

(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, CS = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50Ω unbalanced output of balun, $T_A = +25^{\circ}C$, using the MAX2850 Evaluation Kit.)

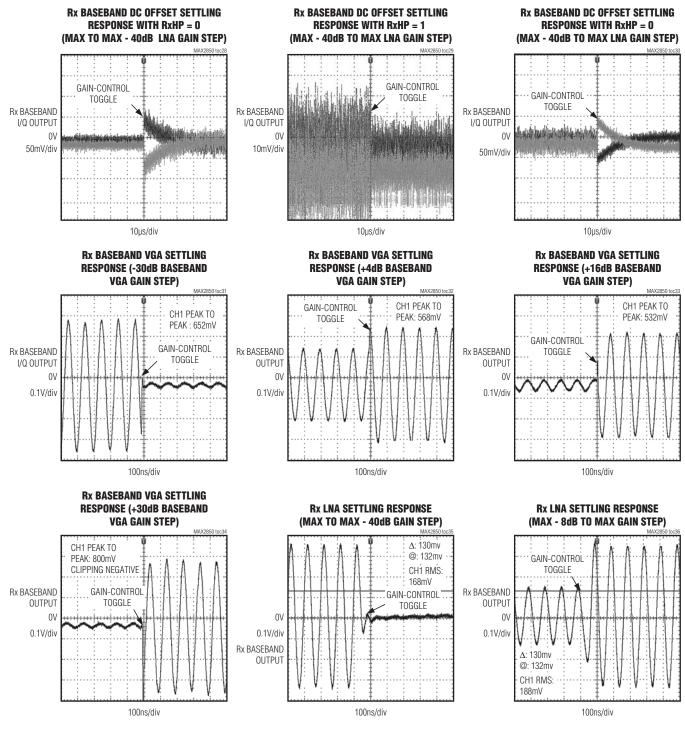


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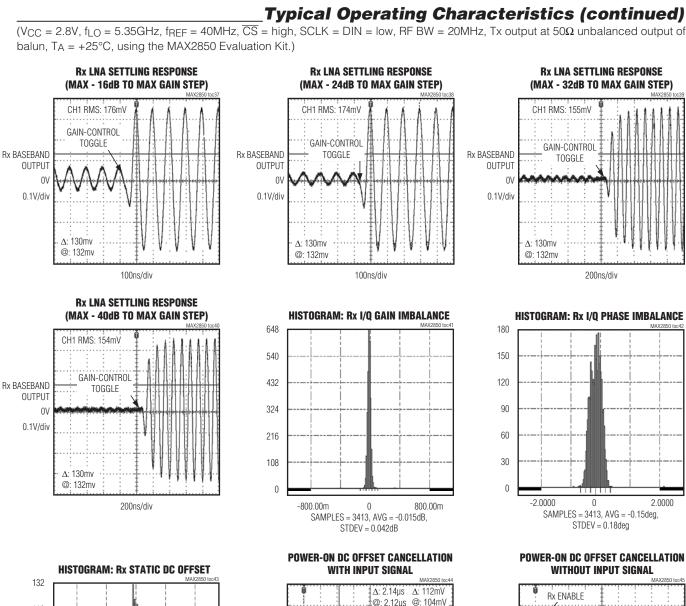
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Typical Operating Characteristics (continued)

 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$



MAX2850



Rx ENABLE

ENGAGE 600kHz HIGHPASS CORNER

Rx BASEBAND OUTPUT

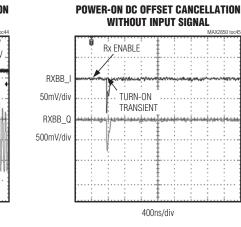
1µs/div

0V

0V

2V/div

0.1V/div



-15.000m

0

SAMPLES = 3413, AVG = -0.5mV, STDFV = 2 14mV

15.000m

110

88

66

44

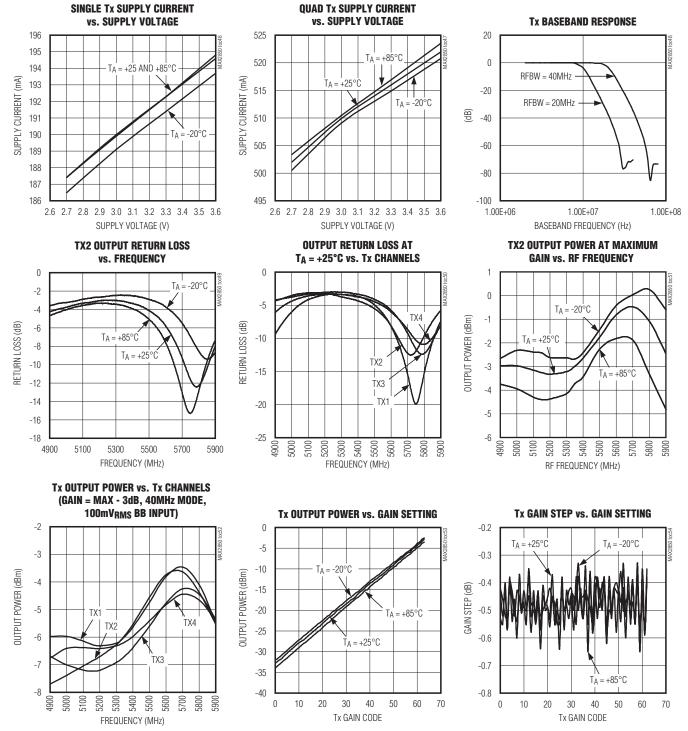
22

0

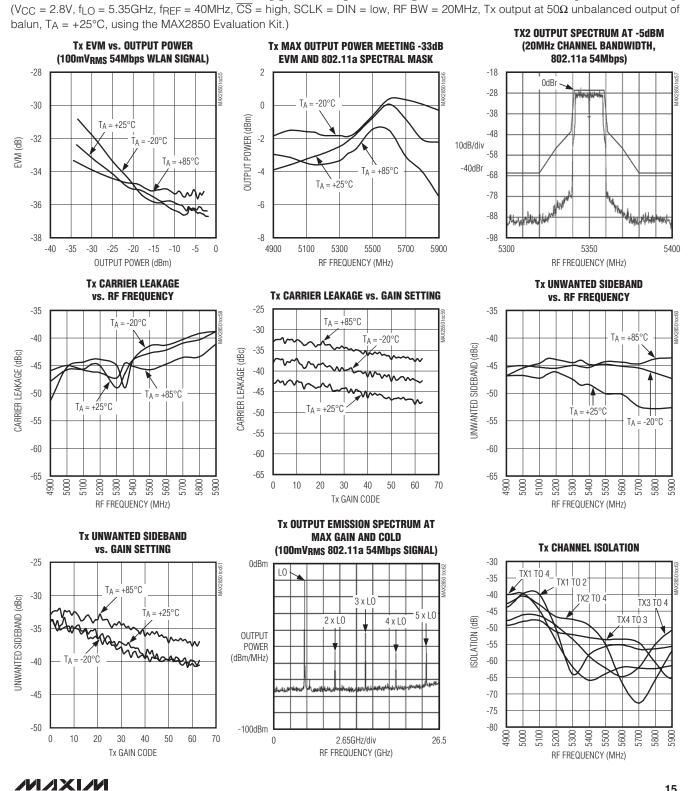
MAX2850

Typical Operating Characteristics (continued)

 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$

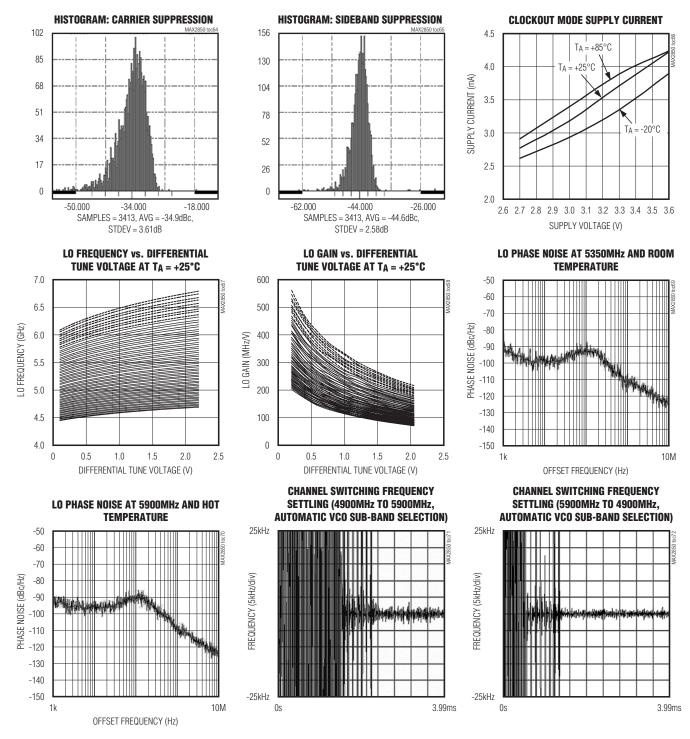


Typical Operating Characteristics (continued)



Typical Operating Characteristics (continued)

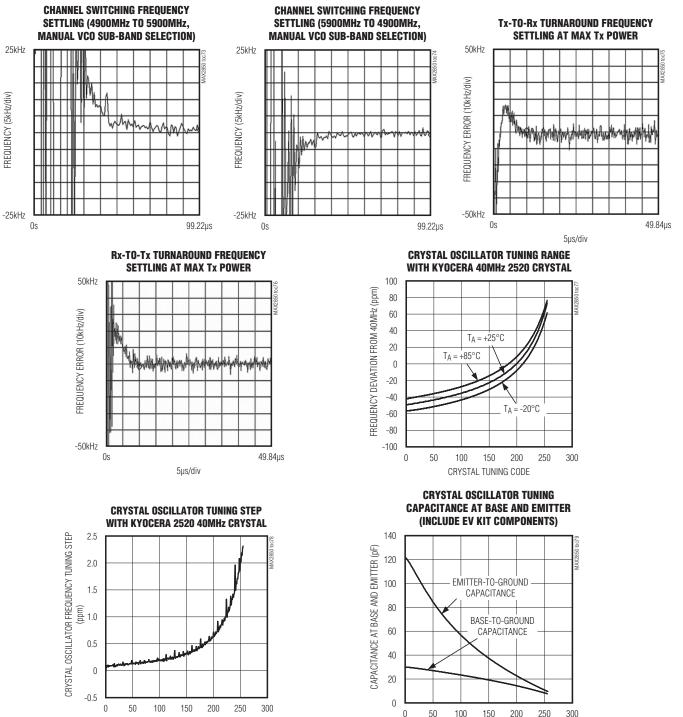
 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$





_Typical Operating Characteristics (continued)

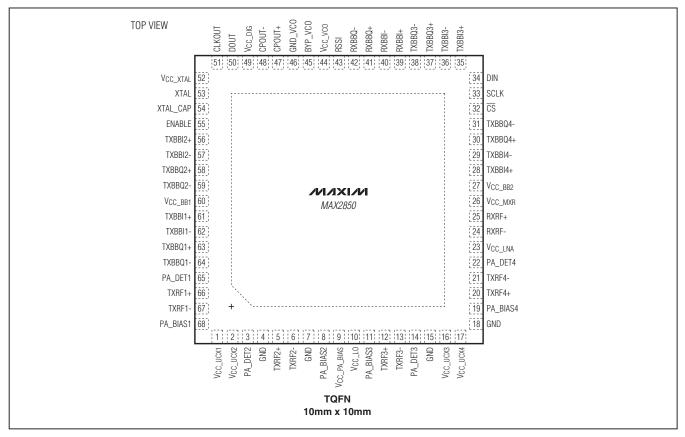
 $(V_{CC} = 2.8V, f_{LO} = 5.35GHz, f_{REF} = 40MHz, \overline{CS} = high, SCLK = DIN = low, RF BW = 20MHz, Tx output at 50\Omega unbalanced output of balun, TA = +25°C, using the MAX2850 Evaluation Kit.)$



M/X/M

XTAL TUNING CODE

Pin Configuration



Pin Description

PIN	NAME	FUNCTION
1	VCC_UCX1	Transmitter 1 Upconverter Supply Voltage. Bypass with a capacitor as close as possible to the pin.
2	VCC_UCX2	Transmitter 2 Upconverter Supply Voltage. Bypass with a capacitor as close as possible to the pin.
3	PA_DET2	External Power-Amplifier Detector Mux Input 2
4	GND	Ground
5	TXRF2+	Transmitter 2 Differential Output. These pins are in open-collector configuration. These pins should
6	TXRF2-	be biased at the supply voltage with differential impedance terminated at 300 Ω .
7	GND	Ground
8	PA_BIAS2	External Power-Amplifier Voltage Bias Output 2
9	VCC_PA_BIAS	External Power-Amplifier Voltage Bias and Detector Mux Supply Voltage. Bypass with a capacitor as close as possible to the pin.
10	Vcc_lo	LO Generation Supply Voltage. Bypass with a capacitor as close as possible to the pin.
11	PA_BIAS3	External Power-Amplifier Voltage Bias Output 3
12	TXRF3+	Transmitter 3 Differential Output. These pins are in open-collector configuration. These pins should
13	TXRF3-	be biased at the supply voltage with differential impedance terminated at 300Ω .
14	PA_DET3	External Power Amplifier Detector Mux Input 3

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_Pin Description (continued)

PIN	NAME	FUNCTION
15	GND	Ground
16	VCC_UCX3	Transmitter 3 Upconverter Supply Voltage. Bypass with a capacitor as close as possible to the pin.
17	VCC_UCX4	Transmitter 4 Upconverter Supply Voltage. Bypass with a capacitor as close as possible to the pin.
18	GND	Ground
19	PA_BIAS4	External Power-Amplifier Voltage Bias Output 4
20	TXRF4+	Transmitter 4 Differential Output. These pins are in open-collector configuration. These pins should
21	TXRF4-	be biased at the supply voltage with differential impedance terminated at 300 Ω .
22	PA_DET4	External Power-Amplifier Detector Mux Input 4
23	VCC_LNA	Receiver LNA Supply Voltage. Bypass with a capacitor as close as possible to the pin.
24	RXRF-	
25	RXRF+	Receiver LNA Differential Input. Input is DC-coupled and biased internally at 1.2V.
26	VCC_MXR	Receiver Downconverter Supply Voltage. Bypass with a capacitor as close as possible to the pin.
27	VCC_BB2	Receiver Baseband Supply Voltage 2. Bypass with a capacitor as close as possible to the pin.
28	TXBBI4+	Transmitter 4 Deschand I Channel Differential Innut
29	TXBBI4-	Transmitter 4 Baseband I-Channel Differential Input
30	TXBBQ4+	Transmitter 4 Deschand O. Channel Differential Innut
31	TXBBQ4-	Transmitter 4 Baseband Q-Channel Differential Input
32	CS	Chip-Select Logic Input of 4-Wire Serial Interface
33	SCLK	Serial-Clock Logic Input of 4-Wire Serial Interface
34	DIN	Data Logic Input of 4-Wire Serial Interface
35	TXBBI3+	Transmitter 2 Reschand I Channel Differential Input
36	TXBBI3-	Transmitter 3 Baseband I-Channel Differential Input
37	TXBBQ3+	Transmitter 2 Reschand O Channel Differential Input
38	TXBBQ3-	Transmitter 3 Baseband Q-Channel Differential Input
39	RXBBI+	Receiver Baseband I-Channel Differential Output
40	RXBBI-	
41	RXBBQ+	Receiver Baseband Q-Channel Differential Output
42	RXBBQ-	
43	RSSI	Receiver Signal-Strength Indicator Output
44	Vcc_vco	VCO Supply Voltage. Bypass with a capacitor as close as possible to the pin.
45	BYP_VCO	On-Chip VCO Regulator Output Bypass. Bypass with an external 1µF capacitor to GND_VCO with minimum PCB trace. Do not connect other circuitry to this pin.
46	GND_VCO	VCO Ground
47	CPOUT+	Differential Charge-Pump Output. Connect the frequency synthesizer's loop filter between CPOUT+
48	CPOUT-	and CPOUT- (see the Typical Operating Circuit).
49	Vcc_dig	Digital Block Supply Voltage. Bypass with a capacitor as close as possible to the pin.
50	DOUT	Data Logic Output of 4-Wire Serial Interface
51	CLKOUT	Reference Clock Buffer Output
52	VCC_XTAL	Crystal Oscillator Supply Voltage. Bypass with a capacitor as close as possible to the pin.
53	XTAL	Crystal Oscillator Base Input. AC-couple crystal unit to this pin.
54	XTAL_CAP	Crystal Oscillator Emitter Node
55	ENABLE	Enable Logic Input



Pin Description (continued)

PIN	NAME	FUNCTION
56	TXBBI2+	Transmitter 2 Reschand I Channel Differential Input
57	TXBBI2-	Transmitter 2 Baseband I-Channel Differential Input
58	TXBBQ2+	Transmitter 2 Reschand O Channel Differential Input
59	TXBBQ2-	Transmitter 2 Baseband Q-Channel Differential Input
60	VCC_BB1	Receiver Baseband Supply Voltage 1. Bypass with a capacitor as close as possible to the pin.
61	TXBBI1+	Transmitter 1 Reschand I Channel Differential Input
62	TXBBI1-	Transmitter 1 Baseband I-Channel Differential Input
63	TXBBQ1+	Transmitter 1 Reschand O Channel Differential Input
64	TXBBQ1-	Transmitter 1 Baseband Q-Channel Differential Input
65	PA_DET1	External Power-Amplifier Detector Mux Input 1
66	TXRF1+	Transmitter 1 Differential Output. These pins are in open-collector configuration. These pins should
67	TXRF1-	be biased at the supply voltage with differential impedance terminated at 300 Ω .
68	PA_BIAS1	External Power-Amplifier Voltage Bias Output 1
	EP	Exposed Pad. Connect to the ground plane with multiple vias for proper operation and heat dissipa- tion. Do not share with any other pin grounds and bypass capacitors' ground.

Table 1. Operating Modes

		ONTROL INPUTS	CIRCUIT BLOCK STATES						
MODE	ENABLE PIN	SPI MAIN ADDRESS 0, D4:D2	Rx PATH	Tx PATH (Note 4)	LO PATH	CLKOUT (Note 5)	Calibration Sections On		
SHUTDOWN	0	XXX	Off	Off	Off	Off	None		
CLKOUT	1	000	Off	Off	Off	On	None		
STANDBY	1	001	Off	Off	On	On	None		
Rx	1	010	On	Off	On	On	None		
Тх	1	011	Off	On	On	On	None		
Tx CALIBRATION	1	100	Off	On	On	On	AM detector + Rx I/Q buffers		
RF LOOPBACK	1	101	On (except LNA)	On	On	On	RF loopback		
BASEBAND LOOPBACK	1	11X	On (except RXRF)	Off	On	On	Tx 4 baseband buffer		

Note 4: PA_BIAS pins may be kept active in nontransmit mode(s) by SPI programming. **Note 5:** CLKOUT signal is active independent of SPI, and is only dependent on the ENABLE pin.

____Detailed Description

-Modes of Operation

The modes of operation for the MAX2850 are shutdown, clockout, standby, receive, transmit, transmitter calibration, RF loopback, and baseband loopback. See Table 1 for a summary of the modes of operation. The logic input

pin ENABLE (pin 55) and SPI Main address 0 D4:D2 control the various modes.

Shutdown Mode

The MAX2850 features a low-power shutdown mode. All circuit blocks are powered down, except the 4-wire serial bus and its internal programmable registers.



MAX2850

Clockout Mode

In clockout mode, only the crystal oscillator signal is active at the CLKOUT pin. The rest of the transceiver is powered down.

Standby Mode

In standby mode, PLL, VCO, and LO generation are on. Tx or Rx modes can be quickly enabled from this mode. Other blocks may be selectively enabled in this mode.

Receive (Rx) Mode

In receive mode, all Rx circuit blocks are powered on and active. Antenna signal is applied; RF is downconverted, filtered, and buffered at Rx baseband I and Q outputs.

Transmit (Tx) Mode

In transmit mode, all Tx circuit blocks are powered on and active. The external PA can be powered on through the PA_BIAS pins after a programmable delay.

Transmit Calibration

In transmit calibration mode, all Tx circuit blocks are powered on and active. The AM detector and receiver I/Q channel buffers are also on. Output signals are routed to Rx baseband I and Q outputs.

The AM detector multiplies the Tx RF output signal with itself. The self-mixing product of the wanted sideband becomes DC voltage and is filtered on-chip. The mixing product between wanted sideband and the carrier leakage forms Ftone at Rx baseband output. The mixing product between the wanted sideband and the unwanted sideband forms 2Ftone at Rx baseband output.

As Tx RF output is self-mixed at the AM detector, the AM detector output responds differently to different gain settings and power levels. When Tx RF output power changes by 1dB through Tx gain control, the AM detector output changes by 2dB as both the wanted sideband and carrier leakage (or unwanted sideband) change by 1dB. When Tx RF output carrier leakage (or unwanted sideband) changes by 1dB while the wanted sideband output power is constant, the AM detector output changes by 1dB only.

RF Loopback

In RF loopback mode, part of the Rx and Tx circuit blocks except the LNA are powered on and active. The transmitter 4 I/Q input signal is upconverted to RF, and the output of the transmitter is fed to the receiver down-converter input. Output signals are delivered to receiver

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4 baseband I/Q outputs. The I/Q lowpass filters in the transmitter signal path are bypassed.

Baseband Loopback

In baseband loopback mode, part of the Rx and Tx baseband circuit blocks are powered and active. The transmitter 4 I/Q input signal is routed to receiver low-pass filter input. Output signals are delivered to receiver 4 baseband I/Q outputs.

Power-On Sequence

Set the ENABLE pin to V_{CC} for 2ms to start the crystal oscillator. Program all SPI addresses according to recommended values. Set SPI Main address 0 D4:D2 from 000 to 001 to engage standby mode. To lock the LO frequency, the user can set SPI in order of Main address 15, Main address 16, and then Main address 17 to trigger VCO sub-band autoacquisition; the acquisition will take 2ms. After the LO frequency is locked, set SPI Main address 0 D4:D2 = 010 and 011 for Rx and Tx operating modes, respectively. Before engaging Rx mode, set Main address 5 D1 = 1 to allow fast DC offset settling. After engaging Rx mode and Rx baseband DC offset settles, the user can set Main address 5 D1 = 0 to complete Rx DC offset cancellation.

Programmable Registers and 4-Wire SPI Interface

The MAX2850 includes 60 programmable 16-bit registers. The most significant bit (MSB) is the read/write selection bit (R/W in Figure 1). The next 5 bits are register address (A4:A0 in Figure 1). The 10 least significant bits (LSBs) are register data (D9:D0 in Figure 1). Register data is loaded through the 4-wire SPI/MICROWIRE™compatible serial interface. MSB of data at the DIN pin is shifted in first and is framed by \overline{CS} . When \overline{CS} is low, the clock is active, and input data is shifted at the rising edge of the clock at SCLK pin. At the \overline{CS} rising edge, the 10-bit data bits are latched into the register selected by address bits. See Figure 1. To support more than a 32-register address using a 5-bit wide address word, the bit 0 of address 0 is used to select whether the 5-bit address word is applied to the main address or local address. The register values are preserved in shutdown mode as long as the power-supply voltage is maintained. There is no power-on SPI register self-reset functionality in the MAX2850, so the user must program all register values after power-up. During the read mode, register data selected by address bits is shifted out to the DOUT pin at the falling edges of the clock.

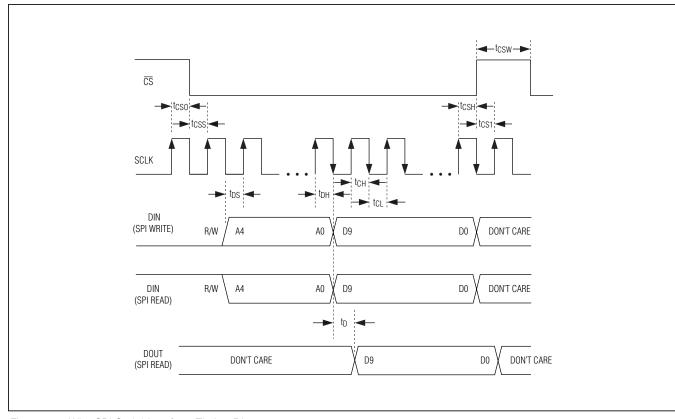


Figure 1. 4-Wire SPI Serial-Interface Timing Diagram

SPI Register Definition

(All values in the register summary table are typical numbers. The MAX2850 SPI does not have a power-on-default selfreset feature; the user must program all SPI addresses for normal operation. Prior to use of any untested settings, contact the factory.)

Table 2. Register Summary

	READ/\	WRITE AN	D ADDRESS		DATA								
REGISTER	Main0_ D0	A4:A0	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Main0	0	00000	W/R	RESERVED		E_TX	<4:1>			MODE<2:0>		RFBW	M/L_SEL
IVIAIIIU		00000	Default	0	1	1	1	1	0	0	0	1	0
Main1	W/R		W/R	RESERVED	RESERVED LNA_GAIN<2:0>				RX_VGA<4:0>				
Maini	0 0000	00001	Default	0	0	1	1	1	1	1	1	1	1
Main2		00010	W/R	RESERVED	RESERVED	RESERVED	LNA_BA	ND<1:0>	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED
IVIAI112	0	00010	Default	0	1	1	0	1	0	0	0	0	0
			W	RESERVED	RESERVED			RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED
Main3	0	00011	R	RESERVED	RESERVED	TS_EN	TS_TRIG	RESERVED		Т	S_READ<4:0>	>	
			Default	0	0	0	0	0	0	0	0	0	0

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	READ/	WRITE AN	D ADDRESS					DA	ТА					
REGISTER	Main0_ D0	A4:A0	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
Main4	0	00100	Reserved	1	1	0	0	0	1	1	1	0	0	
MainE		00404	W/R	RESERVED	RSS	I_MUX_SEL<	2:0>	RESERVED	RESERVED	RESERVED	RESERVED	RXHP	RESERVED	
Main5	0	00101	Default	0	0	0	0	0	0	0	0	0	0	
Main6	0	00110	Reserved	1	1	1	1	1	0	1	0	0	0	
Main7	0	00111	Reserved	0	0	0	0	1	0	0	1	0	0	
Main8	0	01000	W/R	0	0	0	0	0	0	0	0	0	0	
			W/R			TX_GA	N<5:0>				TX_GAIN_PRO)G_SEL<4:1>		
Main9	0	01001	Default	0	0	0	0	0	0	1	1	1	1	
Main10	0	01010	Reserved	0	0	0	0	0	0	0	0	0	0	
			W/R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	E_TX_AM	MD<1:0>	PA_DET_S	SEL<1:0>	
Main11	0	01011	Default	0	0	0	1	1	0	0	0	0	0	
Main13	0	01101	Reserved	0	0	0	0	0	0	0	0	0	0	
			W/R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	DOUT_SEL	RESERVED	
Main14	0	01110	Default	0	1	0	1	1	0	0	0	0	0	
Main15	0	01111	W/R	VAS_ TRIG_EN	RESE	1		1	SYN <u>.</u>	LCONFIG_N<	6:0>			
			Default	1	0	0	1	0	0	0	0	1	0	
			W/R		SYN_CONFIG_F<19:10>						1		I	
Main16	0	10000	Default	1	1	1	0	0	0	0	0	0	0	
			W/R		<u> </u>			SYN_CONF	IG_F<9:0>	<u> </u>	1		<u> </u>	
Main17	0	10001	Default	0	0	0	0	0	0	0	0	0	0	
			W/R	RESERVED	RESERVED				LXTAL_TU	L NE<7:0>	,			
Main18	0	10010	Default	0	0	1	0	0	0	0	0	0	0	
Main19	0	10011	W/R	RESERVED	RESERVED	VAS_ RELOCK_ SEL	VAS_ MODE		I	VAS_SP	1<5:0>		I	
			Read		V/	AS_ADC<2:0	>			VCO_BAN	VD<5:0>			
			Default	0	0	0	1	0	1	1	1	1	1	
Main20	0	10100	Reserved	0	1	1	1	1	0	1	0	1	0	
			Read	RESERVED	RESERVED		DIE_ID<2:0>		RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	
Main21	0	10101	Default	0	0	1	0	1	1	1	1	1	1	
Main22	0	10110	Reserved	0	1	1	0	1	1	1	0	0	0	
Main23	0	10111	Reserved	0	0	0	1	1	0	0	1	0	1	
Main24	0	11000	Reserved	1	0	0	1	0	0	1	1	1	1	
Main25	0	11001	Reserved	1	1	1	0	1	0	1	0	0	0	
Main26	0	11010	Reserved	0	0	0	0	0	1	0	1	0	1	
Main27	0	11011	W/R	DIE_ID_ READ	RESERVED	RESERVED	RESERVED	VAS_VCO_ READ	RESERVED	RESERVED			RESERVED	
			Default	0	1	1	0	0	0	0	0	0	0	
Main28	1		W/R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED		PA_BIAS_	DLY<3:0>	<u>.</u>	
	0	11100												

Table 2. MAX2850 Register Summary (continued)

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Table 2. MAX2850 Register Summary (continued)

	READ/	WRITE AN	D ADDRESS					DA	ТА				
REGISTER	Main0_ D0	A4:A0	WRITE (W)/ READ (R)	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Main29	0	11101	Reserved	0	0	0	0	0	0	0	0	0	0
Main30	0	11110	Reserved	0	0	0	0	0	0	0	0	0	0
Main31	0	11111	Reserved	0	0	0	0	0	0	0	0	0	0
Local1	1	00001	Reserved	0	0	0	0	0	0	0	0	0	0
Local2	1	00010	Reserved	0	0	0	0	0	0	0	0	0	0
Local3	1	00011	Reserved	0	0	0	0	0	0	0	0	0	0
Local4	1	00100	Reserved	1	1	1	0	0	0	0	0	0	0
Local5	1	00101	Reserved	0	0	0	0	0	0	0	0	0	0
Local6	1	00110	Reserved	0	0	0	0	0	0	0	0	0	0
Local7	1	00111	Reserved	0	0	0	0	0	0	0	0	0	0
Local8	1	01000	Reserved	0	1	1	0	1	0	1	0	1	0
Local9	1	01001	Reserved	0	1	0	0	0	1	0	1	0	0
Local10	1	01010	Reserved	1	1	0	1	0	1	0	1	0	0
Local11	1	01011	Reserved	0	0	0	1	1	1	0	0	1	1
Local12	1	01100	Reserved	0	0	0	0	0	0	0	0	0	0
Local13	1	01101	Reserved	0	0	0	0	0	0	0	0	0	0
Local14	1	01110	Reserved	0	0	0	0	0	0	0	0	0	0
Local15	1	01111	Reserved	0	0	0	0	0	0	0	0	0	0
Local16	1	10000	Reserved	0	0	0	0	0	0	0	0	0	0
Local17	1	10001	Reserved	0	0	0	0	0	0	0	0	0	0
Local18	1	10010	Reserved	0	0	0	0	0	0	0	0	0	0
Local19	1	10011	Reserved	0	0	0	0	0	0	0	0	0	0
Local20	1	10100	Reserved	0	0	0	0	0	0	0	0	0	0
Local21	1	10101	Reserved	0	0	0	0	0	0	0	0	0	0
Local22	1	10110	Reserved	0	0	0	0	0	0	0	0	0	0
Local23	1	10111	Reserved	0	0	0	0	0	0	0	0	0	0
Local24	1	11000	Reserved	0	0	1	1	0	0	0	1	0	0
Local25	1	11001	Reserved	0	1	0	0	1	0	1	0	1	1
Local26	1	11010	Reserved	0	1	0	1	1	0	0	1	0	1
Local27	1	11011	W/R	RESERVED	TX_AMD_ BB_GAIN	TX_AMD_ <1:							
			Default	0	0	0	0	0	0	0	0	0	0
Local28	1	11100	Reserved	0	0	0	0	0	0	0	1	0	0
Local31	1	11111	Reserved	0	0	0	0	0	0	0	0	0	0

Table 3. Main Address 0: (A4:A0 = 00000)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9	Reserved bits; set to default
E_TX<4:1>	D8:D5	Tx MIMO Channel Select Select Tx channels independently. 0 = Not select 1 = Select in Tx, Tx calibration, or RF loopback modes 1111 = Default
MODE<2:0>	D4:D2	IC Operating Mode Select 000 = Clockout (default) 001 = Standby 010 = Rx 011 = Tx 100 = Tx calibration 101 = RF loopback 11x = Baseband loopback
RFBW	D1	RF Bandwidth 0 = 20MHz 1 = 40MHz (default)
M/L_SEL	D0	Main or Local Address Select 0 = Main registers (default) 1 = Local registers

Table 4. Main Address 1: (A4:A0 = 00001, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D8	Reserved bits; set to default
LNA_GAIN<2:0>	D7:D5	LNA Gain Control Active when Rx channel is selected by corresponding RX_PATH_UNMASK<5:1> bits in Main address 6 D9:D5. 000 = Maximum - 40dB 001 = Maximum - 32dB 100 = Maximum - 32dB 101 = Maximum - 24dB 101 = Maximum - 16dB 110 = Maximum - 8dB 111 = Maximum gain (default)
VGA_GAIN<4:0>	D4:D0	Rx VGA Gain Control Active when Rx channel is selected by corresponding RX_PATH_UNMASK<5:1> bits in Main address 6 D9:D5. 00000 = Minimum gain 00001 = Minimum + 2dB 01110 = Minimum + 28dB 01111 = Minimum + 30dB 1xxxx = Minimum + 30dB (default)

Table 5. Main Address 2: (A4:A0 = 00010, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D7	Reserved bits; set to default
LNA_BAND<1:0>	D6:D5	LNA Frequency Band Switch 00 = 4.9GHz~5.2GHz 01 = 5.2GHz~5.5GHz (default) 10 = 5.5GHz~5.8GHz 11 = 5.8GHz~5.9GHz
RESERVED	D4:D0	Reserved bits; set to default

Table 6. Main Address 3: (A4:A0 = 00011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D8	Reserved bits; set to default
TS_EN	D7	Temperature Sensor Enable 0 = Disable (default) 1 = Enable except shutdown or clockout mode
TS_TRIG	D6	Temperature Sensor Reading Trigger 0 = Not trigger (default) 1 = Trigger temperature reading
RESERVED	D5	Reserved bits; set to default
TS_READ<4:0>	D4:D0	SPI readback only. Temperature sensor reading.

Table 7. Main Address 5: (A4:A0 = 00101, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9	Reserved bits; set to default
RSSI_MUX_SEL<2:0>	D8:D6	RSSI Output Select 000 = Baseband RSSI (default) 001 = Do not use 010 = Do not use 011 = Do not use 100 = Rx RF detector 101 = Do not use 110 = PA power-detector mux output 111 = Do not use
RESERVED	D5:D2	Reserved bits, set to default
RXHP	D1	 Rx VGA Highpass Corner Select after Rx Turn-On RXHP starts at 1 during Rx gain adjustment, and set to 0 after gain is adjusted. 0 = 10kHz highpass corner after Rx gain is adjusted (default) 1 = 600kHz highpass corner during Rx gain adjustment
RESERVED	D0	Reserved bits; set to default

Table 8. Main Address 9: (A4:A0 = 01001, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
TX_GAIN<5:0>	D9:D4	Tx VGA Gain Control Tx channel is selected by Main address 9 D3:D0. 000000 = Minimum gain (default) 111111 = Minimum gain + 31.5dB
TX_GAIN_PROG_SEL<4:1>	D3:D0	Tx Channel Gain Programming Select Gain is determined by Main address 9 D9:D4. 0 = Not selected 1 = Selected 1111 = Default

Table 9. Main Address 11: (A4:A0 = 01011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D4	Reserved bits; set to default
E_TX_AMD<1:0>	D3:D2	Tx Calibration AM Detector Channel Select Only active in Tx calibration mode. 00 = Select TX1 (default) 01 = Select TX2 10 = Select TX3 11 = Select TX4
PA_DET_SEL<1:0>	D1:D0	PA Power-Detector Mux Output Select 00 = Select PA_DET1 (default) 01 = Select PA_DET2 10 = Select PA_DET3 11 = Select PA_DET4

Table 10. Main Address 14: (A4:A0 = 01110, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D2	Reserved bits; set to default
DOUT_SEL	D1	DOUT Pin Output Select 0 = PLL lock detect (default) 1 = SPI readback
RESERVED	D0	Reserved bits; set to default

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Table 11. Main Address 15: (A4:A0 = 01111, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
VAS_TRIG_EN	D9	Enable VCO Sub-Band Acquisition Triggered by SYN_CONFIG_F<9:0> (Main Address 17) Programming 0 = Disable for small frequency adjustment (i.e., ~100kHz) 1 = Enable for channel switching (default)
RESERVED	D8:D7	Reserved bits; set to default
SYN_CONFIG_N<6:0>	D6:D0	Integer Divide Ratio 1000010 = Default

Table 12. Main Address 16: (A4:A0 = 10000, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
SYN_CONFIG_F<19:10>	D9:D0	Fractional Divide Ratio MSBs 1110000000 = Default

Table 13. Main Address 17: (A4:A0 = 10001, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
SYN_CONFIG_F<9:0>	D9:D0	Fractional Divide Ratio LSBs 000000000 = Default

Table 14. Main Address 18: (A4:A0 = 10010, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D8	Reserved bits; set to default
XTAL_TUNE<7:0>	D7:D0	Crystal Oscillator Frequency Tuning 00000000 = Minimum frequency 10000000 = Default 11111111 = Maximum frequency

Table 15. Main Address 19: (A4:A0 = 10011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D8	Reserved bits; set to default
VAS_RELOCK_SEL	D7	VAS Relock Select 0 = Start at sub-band selected by VAS_SPI<5:0> (Main address 19 D5:D0) (default) 1 = Start at current sub-band
VAS_MODE	D6	VCO Subband Select 0 = By VAS_SPI<5:0> (Main address 19 D5:D0) 1 = By on-chip VCO autoselect (VAS) (default)

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Table 15. Main Address 19: (A4:A0 = 10011, Main Address 0 D0 = 0) (continued)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
VAS_SPI<5:0>	D5:D0	VCO Autoselect Sub-Band Input Select VCO sub-band when VAS_MODE (Main address 19 D6) = 0. Select initial VCO sub-band for autoacquisition when VAS_MODE = 1. 000000 = Minimum frequency sub-band 011111 = Default 111111 = Maximum frequency sub-band
VAS_ADC<2:0> (Readback Only)	D8:D6	Read VCO Autoselect Tune Voltage ADC Output Active when VCO_VAS_RB (Main address 27 D5) = 1. 000 = Lower than lock range and at risk of unlock 001 = Lower than acquisition range and maintain lock 010 or 101 = Within acquisition range and maintain lock 110 = Higher than acquisition range and maintain lock 111 = Higher than lock range and at risk of unlock
VCO_BAND<5:0> (Readback Only)	D5:D0	Read the Current Acquired VCO Sub-Band by VCO Autoselect Active when VCO_VAS_RB (Main address 27 D5) = 1.

Table 16. Main Address 21: (A4:A0 = 10101, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D0	Reserved bits; set to default
DIE_ID<2:0> (Readback Only)	D7:D5	Read Revision ID at Main Address 21 D7:D5 Active when DIE_ID_READ (Main address 27 D9) = 1. 000 = Pass1 001 = Pass2

Table 17. Main Address 27: (A4:A0 = 11011, Main Address 0 D0 = 0)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
DIE_ID_READ	D9	Die ID Readback Select 0 = Main address 21 D9:D0 reads its own values (default) 1 = Main address 21 D7:D5 reads revision ID
RESERVED	D8:D6	Reserved bits, set to default
VAS_VCO_READ	D5	VAS ADC and VCO Sub-Band Readback Select 0 = Main address 19 D9:D0 reads its own values (default). 1 = Main address 19 D8:D6 reads VAS_ADC<2:0>; Main address 19 D5:D0 reads VCO_BAND<5:0>.
RESERVED	D4:D0	Reserved bits; set to default

Table 18. Main Address 28: (A4:A0 = 11100, Main Address 0 D0 = 0)

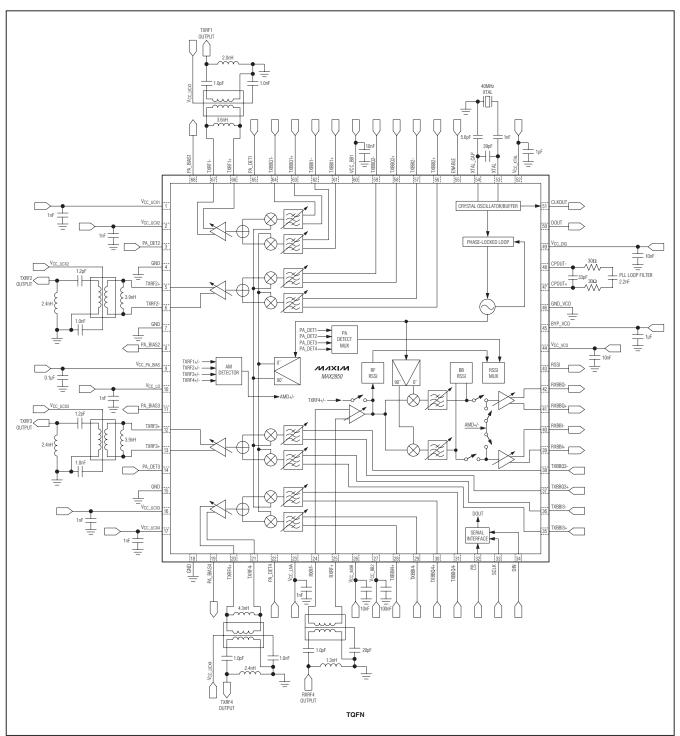
BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D4	Reserved bits; set to default
PA_BIAS_DLY<3:0>	D3:D0	PA_BIAS Turn-On Delay 0000 = 0μs 0001 = 0μs 0010 = 0.5μs 0011 = 1.0μs (default) 1111 = 7.0μs

Table 19. Local Address 27: (A4:A0 = 11011, Main Address 0 D0 = 1)

BIT NAME	BIT LOCATION (D0 = LSB)	DESCRIPTION
RESERVED	D9:D3	Reserved bits, set to default
TX_AMD_BB_GAIN	D2	Tx Calibration AM Detector Baseband Gain 0 = Minimum gain (default) 1 = Minimum gain + 5dB
TX_AMD_RF_GAIN	D1:D0	Tx Calibration AM Detector RF Gain 00 = Minimum gain (default) 01 = Minimum gain + 14dB rise at output 1x = Minimum gain + 28dB rise at output

5GHz, 4-Channel MIMO Transmitter

Typical Operating Circuit



MAX2850

Chip Information

Package Information

PROCESS: BICMOS

For the latest package outline information and land patterns, go to <u>www.maxim-ic.com/packages</u>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
68 TQFN-EP	T6800+2	<u>21-0142</u>

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/09	Initial release	—
1	3/10	Modified EC table to support single-pass room test flow	2, 3, 5, 6, 8

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